

NEW CLAIMS

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103 43. The method of claim 1, further comprising providing a protective layer on the substrate.

103 44. The method of claim 43, wherein the substrate is a low temperature substrate, and the protective layer is a protective thermal barrier for preventing damage to the substrate during sintering and for enhancing adhesion of the material to the substrate.

103 45. The method of claim 44, wherein the thermal barrier is an aerogel.

103 46. The method of claim 44, wherein the substrate, the material, and the protective thermal barrier form an electronic component.

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